

Template	Last Amendment Date	Country
Role Profile	May 2007	UK

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Role Profile Document

Role Title	Assembly Engineering Group Leader	Location	CCD
Reporting To	J Turton	Grade	M2

Context and Purpose

As Assembly Engineering group leader you will be responsible for the supervision and development of the Process Engineering and Package Integration teams, ensuring full and timely completion of customer driven projects as well as providing support to production via Line Engineers. The group contains two functional elements, one focussed on new process development and new product introduction, the other focussed on line engineering support to CCD Post processing.

Main Accountabilities	Competencies
<ul style="list-style-type: none"> Responsible for resource planning and allocation to meet current and predicted project requirements Technical lead for the group, ensuring continuous development and drive towards best practice processes Responsible for carrying out performance management reviews and driving forward training and development plans for the group, within budgetary constraints Responsible for developing and maintaining Key Performance Indicators (KPIs) for the group and driving year on year improvements to meet performance targets Drive the recruitment process for high calibre engineers to meet business demands and succession plans in own area Manage the team to provide technical and cost information in to the bid process in order to minimise technical risk and ensure adherence to timescales Manage the team to operate within Project or PV budgetary constraints and drive efficiency improvement activities to reduce cost and time to market. 	<ul style="list-style-type: none"> Planning for results Customer First Leadership Improvement Persuasive communication Planning for Results Improvement Adaptability Building Relationships Planning for results Customer First Commercial Judgement Commercial Judgement Leadership

Essential Experience

Degree qualified in Physics, Engineering or related discipline, with a minimum of 5 years experience in related job roles

Experience of Semiconductor packaging technologies and ideally a working knowledge of wire bonding and die attach processes
Strong Interpersonal skills with a demonstrated ability to meet project commitments and drive improvement activities